

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-26. (Canceled)

27. (Currently Amended) A wafer double-side polishing apparatus comprising: ~~at least~~
_____ a carrier plate having wafer holding holes, a center of each wafer holding hole
disposed along a first pitch circle having a first diameter;
_____ upper and lower turn tables to which polishing pads are attached; and
_____ a slurry supply means;
_____ wherein:
_____ with wafers held in the wafer holding holes, the carrier plate being moved between
the upper and lower turn tables while supplying slurry, to simultaneously polish both front and back
surfaces of ~~wafers; wafers, wherein a PCD of~~
_____ the upper turn table further comprising a plurality of load supporting points disposed
along a second pitch circle having a second diameter equal to the first diameter, the load supporting
points configured to receive and distribute applied force to the upper turn table, ~~that is a diameter of a~~
circle joining load supporting points of the upper turn table coincides with a PCD of centers of the
wafer holding holes on the carrier plate that is a diameter of a circle joining each center of the wafer
holding holes on the carrier plate.

28. (Previously Presented) The wafer double-side polishing apparatus according to claim 27, wherein the motion of the carrier plate is a circular motion not accompanied by rotation of the carrier plate.

29. (Canceled)

30. (Currently Amended) The wafer double-side polishing apparatus according to claim 27, wherein: ~~a PCD of~~

_____ the lower turn table further comprising a plurality of load supporting points disposed along a third pitch circle having a third diameter equal to the first diameter, the load supporting points configured to receive and distribute applied force to the upper turn table, that is a diameter of a circle joining load supporting points of the lower turn table coincides with the PCD of the upper turn table load supporting points.

31. (Canceled)

32. (Currently Amended) A wafer double-side polishing method comprising:
 _____ holding wafers on a carrier plate ~~on which are formed~~ having wafer holding holes for holding wafers, a center of each wafer holding hole disposed along a first pitch circle having a first diameter; and, while supplying slurry, and
 _____ moving the carrier plate between upper and lower turn tables to which polishing pads are attached, while supplying slurry, to simultaneously polish both front and back surfaces of the ~~wafers; wafers,~~
 _____ wherein:

_____ the upper turn table further comprising a plurality of load supporting points disposed along a second pitch circle having a second diameter equal to the first diameter, the load supporting points configured to receive and distribute applied force to the upper turn table; and
 _____ the wafers are polished ~~with~~ while applying force to the load supporting points of the upper turn table, causing a PCD of upper turn table load supporting points that is a diameter of a circle joining load supporting points of the upper turn table and a PCD of wafer centers that is a diameter of a circle joining centers of the wafers held by the carrier plate to coincide with each other.

33. (Previously Presented) The wafer double-side polishing method according to claim 32, wherein the motion of the carrier plate is a circular motion not accompanied by rotation of the carrier plate.

34. (Canceled)

35. (Currently Amended) The wafer double-side polishing method according claim 32, wherein;

the lower turn table further comprising a plurality of load supporting points disposed along a third pitch circle having a third diameter equal to the first diameter, the load supporting points configured to receive and distribute applied force to the lower turn table; and

the wafers are polished while applying force to the load supporting points of the lower turn table. ~~a PCD of lower turn table load supporting points that is a diameter of a circle joining load supporting points of the lower turn table is caused to coincide with the PCD of the upper turn table load supporting points.~~

36. (Canceled)

37. (Previously Presented) The wafer double-side polishing method according to claim 32, wherein during the wafer polishing, the wafers are polished while controlling polishing conditions.

38. (Canceled)

39. (Previously Presented) The wafer double-side polishing method according to claim 37, wherein the polishing condition control is performed by controlling the temperature of the upper turn table and/or the lower turn table.

40-63. (Canceled)